



100V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BVDSS	Ros(on) Max	I _D Tc = +25°C
4001/	14.5mΩ @ V _{GS} = 10V	56A
100V	19.5mΩ @ V _{GS} = 6V	49A

Description and Applications

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize R_{DS(ON)} yet maintain superior switching performance. This device is ideal for use in:

- Motor controls
- DC-DC converters
- Power managements

Features

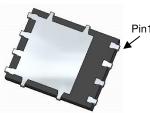
- Rated to +175°C—Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Thermally Efficient Package—Cooler Running Applications
- Low Rds(ON)—Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
 - https://www.diodes.com/quality/product-definitions/
- An automotive-compliant part is available under separate datasheet (DMTH10H015SPSQ)

Mechanical Data

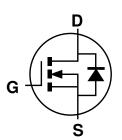
- Package: PowerDI[®]5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead-Frame.
 Solderable per MIL-STD-202, Method 208[®]
- Weight: 0.097 grams (Approximate)



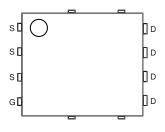




Bottom View



Internal Schematic



Top View Pin Configuration

Site 2:

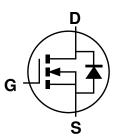
PowerDI5060-8/SWP (Type UX)



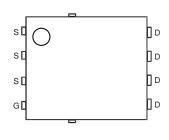
Top View



Bottom View



Internal Schematic



Top View Pin Configuration

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



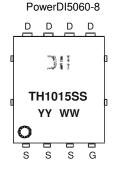
Ordering Information (Note 4)

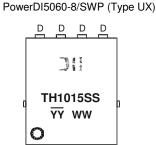
Part Number	Dookogo	Packing		
Part Number	Package	Qty.	Carrier	
DMTH10H015SPS-13	PowerDI5060-8	2,500	Tape & Reel	
DMTH10H015SPS-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel	

Note:

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





 = Manufacturer's Marking TH1015SS = Product Type Marking Code YYWW or $\overline{YY}WW = Date Code Marking$ YY or \overline{YY} = Last Two Digits of Year (ex: 23 = 2023) WW = Week Code (01 to 53)

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	100	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 5) V _{GS} = 10V	lo	56 39	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	120	Α
Maximum Continuous Body Diode Forward Current (Note 5)			Is	56	Α
Avalanche Current (Note 7), L = 3mH			las	7.5	Α
Avalanche Energy (Note 7), L = 3mH			Eas	85	mJ
Avalanche Current, L = 0.1mH			las	15.8	Α
Avalanche Energy, L = 0.1mH			Eas	12.5	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	P _D	2.7	W
Thermal Resistance, Junction to Ambient (Note 6)		RθJA	55	°C/W
Total Power Dissipation (Note 5)	Tc = +25°C	PD	94	W
Thermal Resistance, Junction to Case (Note 5)	•	Rejc	1.6	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Notes:

- 5. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1 inch square copper plate.
- 7. Guaranteed by design. Not subject to product testing.



Electrical Characteristics (@ TA = +25°C, unless otherwise specified.)

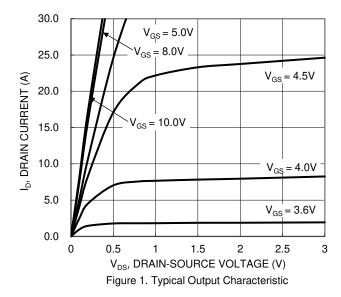
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	100	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	$V_{DS} = 80V$, $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	2	_	4	٧	$V_{DS}=V_{GS},\ I_D=250\mu A$	
Static Drain-Source On-Resistance	Dagger	_	11.3	14.5	mΩ	$V_{GS} = 10V, I_{D} = 20A$	
Static Drain-Source Off-Nesistance	RDS(ON)	_	14.7	19.5	11122	$V_{GS} = 6V, I_{D} = 20A$	
Diode Forward Voltage	V_{SD}	_	0.9	1.3	٧	$V_{GS} = 0V, I_S = 20A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	Ciss	_	2343			V _{DS} = 50V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	_	487	_	pF		
Reverse Transfer Capacitance	Crss	_	26				
Gate Resistance	R_g	_	0.69		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	30.1			V 50V I- 10A	
Gate-Source Charge	Qgs	_	7.5		nC	V _{DD} = 50V, I _D = 10A, V _{GS} = 10V	
Gate-Drain Charge	Q_{gd}	_	6.5	_			
Turn-On Delay Time	td(on)	_	9.8			$V_{DD} = 50V, \ V_{GS} = 10V,$ $I_{D} = 10A, \ R_{G} = 6\Omega$	
Turn-On Rise Time	t _R	_	7.8		ns		
Turn-Off Delay Time	tD(OFF)	_	22.5				
Turn-Off Fall Time	tr	_	9.6	_			
Reverse Recovery Time	trr	_	43.1	_	ns	I _F = 10A, di/dt = 100A/μs	
Reverse Recovery Charge	Qrr	_	65.1	_	nC	F = 10A, α/αι = 100A/μ5	

Notes:

^{7.} Guaranteed by design. Not subject to product testing. 8. Short duration pulse test used to minimize self-heating effect.







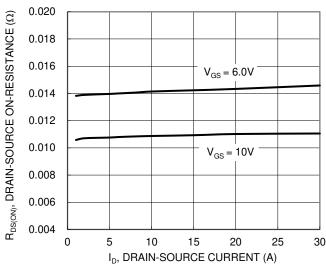


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

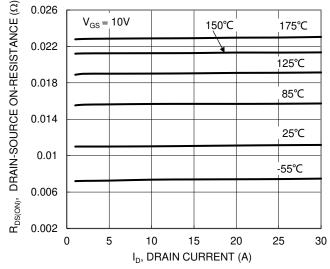


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

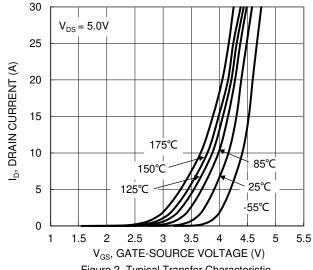
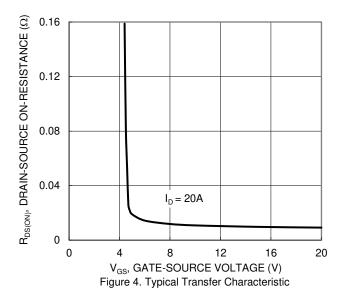


Figure 2. Typical Transfer Characteristic



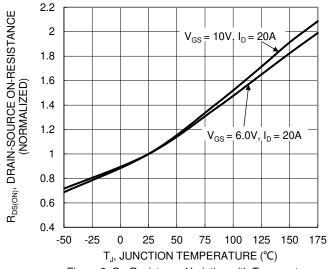
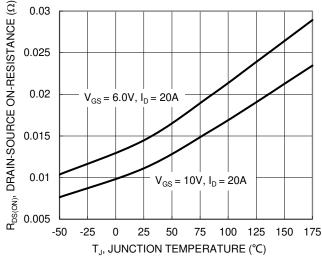
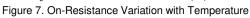


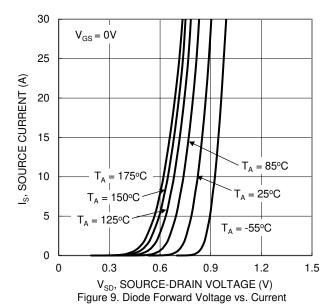
Figure 6. On-Resistance Variation with Temperature











8
6
V_{DS} = 50V, I_D = 10A
2
0

 $\label{eq:Qg} \textbf{Q}_{g} \; (\text{nC})$ Figure 11. Gate Charge

20

25

30

15

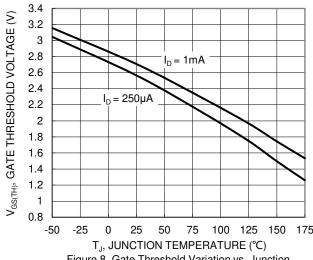
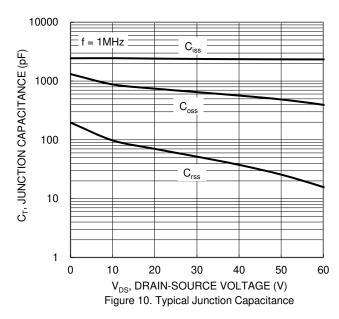


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 R_{DS(ON)} Limited 100 ID, DRAIN CURRENT (A) 10 1 $T_{J(Max)} = 175^{\circ}C$ = 100 ms $T_C = 25^{\circ}C$ Single Pulse DUT on 1*MRP $P_W = 1s$ Board $V_{GS} = 10V$ 0.01 0.1 10 100 1000 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area

5 of 9 www.diodes.com

35

5

10

10



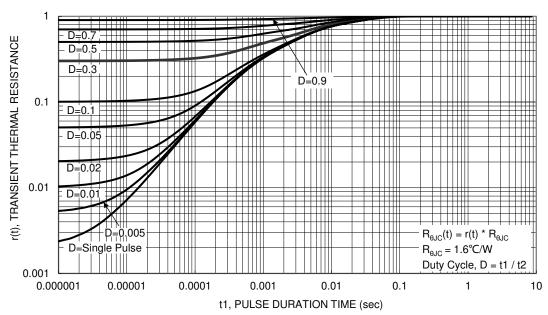


Figure 13. Transient Thermal Resistance



D

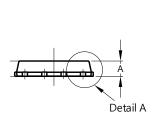
D1

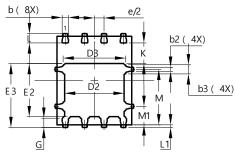
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

Site 1:

Detail A θ(4X) 01 (4X)





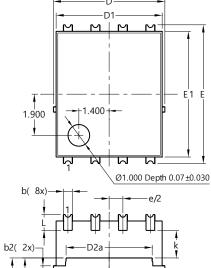
PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A 1	0.00	0.05	-	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D	1,	5.15 BSC	;	
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е	(6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е	•	1.27 BSC	;	
G	0.51	0.71	0.61	
K	0.51	-	-	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
М	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12°	11°	
Θ1	6°	8°	7°	
All Dimensions in mm				

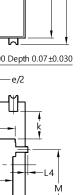
Site 2:

E2a |

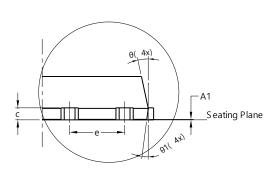
PowerDI5060-8/SWP (Type UX)

PowerDI5060-8

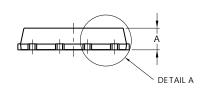




-b4(8x)



DETAIL A



PowerDI5060-8/SWP				
(Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A 1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4).25REF		
С	0.230	0.330	0.277	
D		.15 BS0		
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0		
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1	.27BSC)	
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L1a	0.050REF			
L4	0.025	0.225	0.125	
M	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				



Suggested Pad Layout

 $Please \ see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

Site 1:

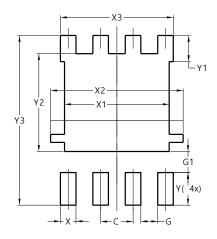
X4 — Y2 — Y3 — Y4 — X1 — Y6 — G1

Dimensions	Value (in mm)
	, ,
С	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Υ	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

PowerDI5060-8/SWP (Type UX)

PowerDI5060-8



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	4.100		
X2	5.190		
Х3	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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